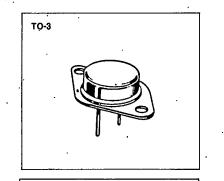


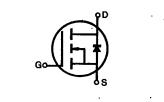
FEATURES

- Low R_{DS(on)} at high voltage
- Improved inductive ruggedness.
- Excellent high voltage stability
- Fast switching times
- Rugged polysilicon gate cell structure
- Low input capacitance
- Extended safe operating area
- Improved high temperature reliability
- TO-3 package (High voltage)

PRODUCT SUMMARY

Part Number	VDS	R _{DS(on)}	lD		
IRF420	.500V	3.0 D	2.5A		
IRF421	450V	3.0 û	2.5A		
IRF422	500V	4.0 û	2.0A		
IRF423	450V	4.0 û	2.0A		





MAXIMUM RATINGS

Characteristic	Symbol	IRF420	IRF421	IRF422	IRF423	Unit
Drain-Source Voltage (1)	VDSS	500	450	500	450	Vdc
Drain-Gate Voltage (R _{GS} =1.0MΩ) (1)	VDGR	500	450	500	450	Vdc
Gate-Source Voltage	V _{GS}		Vdc			
Continuous Drain Current T _C =25°C	۱D	2.5	2.5	2.0	2.0	Adc
Continuous Drain Current T _C =100°C	lo	1.5	1.5	1.0	1.0	Adc
Drain Current-Pulsed (3)	Ідм	10	10	8.0	8.0	Adc
Gate Current-Pulsed	Ідм		Adc			
Total Power Dissipation @ T _C =25°C Derate above 25°C	PD		Watts W/°C			
Operating and Storage Junction Temperature Range	T _J , ['] Tstg		°C			
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	TL · 300					

Notes: (1) TJ=25°C to 150°C

(2) Pulse test: Pulse width≤300µs, Duty Cycle≤2%
(3) Repetitive rating: Pulse width limited by max. junction temperature

SAMSUNG SEMICONDUCTOR

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N-CHANNEL **POWER MOSFETS**

ELECTRICAL CHARACTERISTICS (Tc=25°C unless otherwise specified)

Characteristic	Symbol	Туре	Min	Тур	Max	Units	Test Conditions	
Drain-Source Breakdown	BVDSS	IRF420 IRF422	500	-	-	v	V _{GS} =0V	
Voltage		IRF421 IRF423	450	I	_	v	l _D =250μA	
Gate Threshold Voltage	V _{GS(th)}	ALL	2.0	-	4.0	V	V _{DS} =V _{GS} , I _D =250µA	
Gate-Source Leakage Forward	IGSS	ALL	_	—	100	nA	V _{GS} =20V	
Gate-Source Leakage Reverse	lgss	ALL	1	1	-100	nA	V _{GS} =-20V	
Zero Gate Voltage	loss .	ALL	I	1	250	μA	V _{DS} =Max. Rating, V _{GS} =0V	
Drain Current	-055	7166	-	1	1000	μA	V_{DS} =Max. Rating×0.8, V_{GS} =0V, T_C =125°C	
On-State Drain-Source	I _{D{on}}	IRF420 IRF421	2.5	-	-	A	V _{DS} >I _{D(on)} XR _{DS(on) max.} , V _{GS} =10V	
Current (2)	iD(on)	IRF422 IRF423	2.0	· _	-	. A		
Static Drain-Source On-State	R _{DS(on)}	IRF420 IRF421	-	2.5	3.0	Ω	V _{GS} =10V, I _D =1.0A	
Resistance (2)	US(on)	IRF422 IRF423	1	3.0	4.0	Q	VGS-10V, ID-1.0A	
Forward Transconductance (2)	Qfs	ALL	1.0	1.75	_	8	V _{DS} >I _{D(on)} ×R _{DS(on) max.} , I _D =1.0A	
Input Capacitance	Ciss	ALL	1	300	600	рF	·	
Output Capacitance	Coss	ALL	-	75	150	pF	V _{GS} =0V, V _{DS} =25V, f=1.0MHz	
Reverse Transfer Ĉapacitance	Crss	ALL	Ι	20	40	рF		
Turn-On Delay Time	t _{d(on)}	ALL	Ι	-	60	ns		
Rise Time	tr	ALL	-	-	50	ns	$V_{DD}=0.5BV_{DSS}$, $I_D=1.0A$, $Z_O=50 \Omega$, (MOSFET switching times are essentially independent of operating temperature.)	
Turn-Off Delay Time	td(off)	ALL	-	-	60	ns		
Fall Time	tr	ALL	-	-	30	ns		
Total Gate Charge (Gate-Source Plus Gate-Drain)	Qg	ALL	-	11	15		V_{GS} =10V, I_D =3.0A, V_{DS} =0.8 Max. Rating (Gate charge is essentially independent of operating temperature.)	
Gate-Source Charge	Qgs	ALL	-	5.0	-			
Gate-Drain ("Miller") Charge	Q _{gd}	ALL	-	6.0	-	nC		

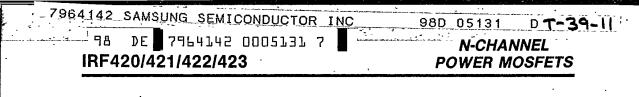
THERMAL RESISTANCE

Junction-to-Case	RthJC	ALL		-	3.12	K/W	
Case-to-Sink	RthCS	ALL		0.1	1	K/W	Mounting surface flat, smooth, and greased
Junction-to-Ambient	RthJA	ALL	-	—	30	K/W	Free Air Operation

Notes: (1) TJ=25°C to 150°C (2) Pulse test: Pulse width≤300µs, Duty Cycle≤2% (3) Repetitive rating: Pulse width limited by max. junction temperature

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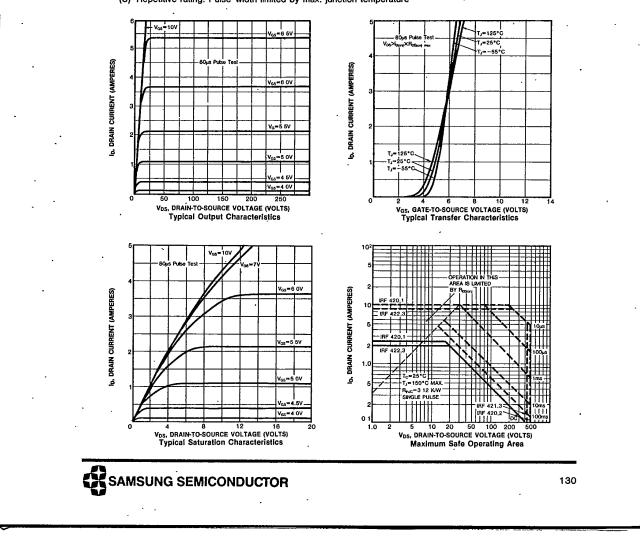
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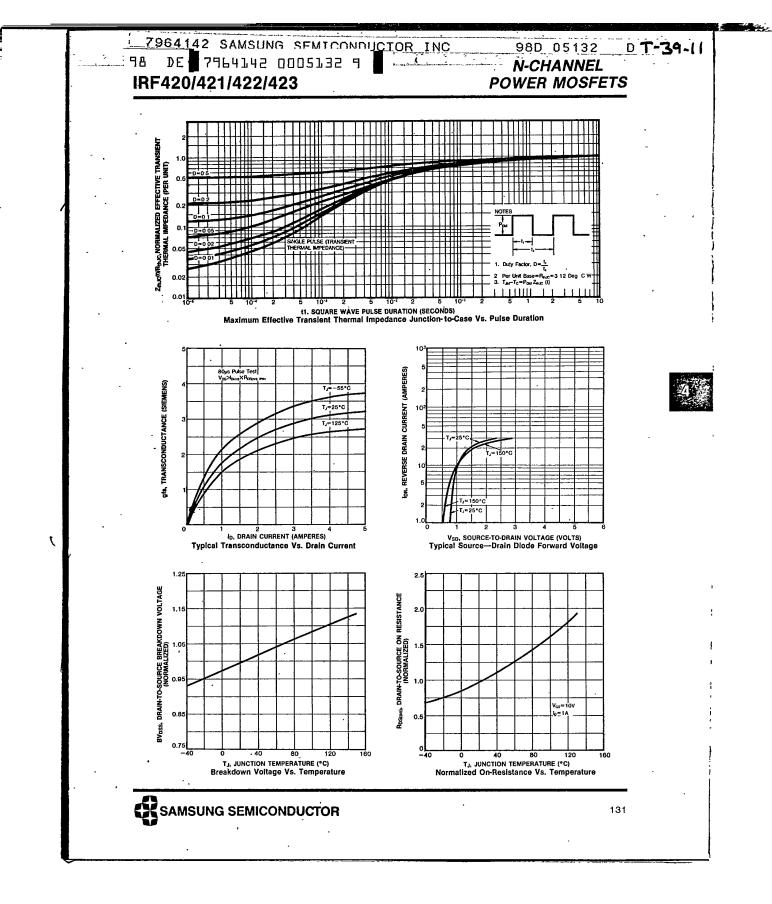
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristic	Symbol	Туре	Min	Тур	Max	Units	Test Conditions
Continuous Source Current	ls	IRF420 IRF421	-	-	2.5	A	
(Body Diode)	IS	IRF422 IRF423	-	-	2.0	- A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier
Pulse Source Current I _{SM} (Body Diode) (3)		IRF420 IRF421	_	_	10	A	
	SM	IRF422 IRF423	_	-	8.0	A	
Diode Forward Voltage (2)	Vsp	IRF420 IRF421	-	-	1.4	v	T _C =25°C, I _S =2.5A, V _{GS} =0V
	. • SD	IRF422 IRF423	-	-	1.3	v .	T _C =25°C, I _S =2.0A, V _{GS} =0V
Reverse Recovery Time	· trr	ALL		600	_	ns	TJ=150°C, IF=2.5A, dIF/dt=100A/µs

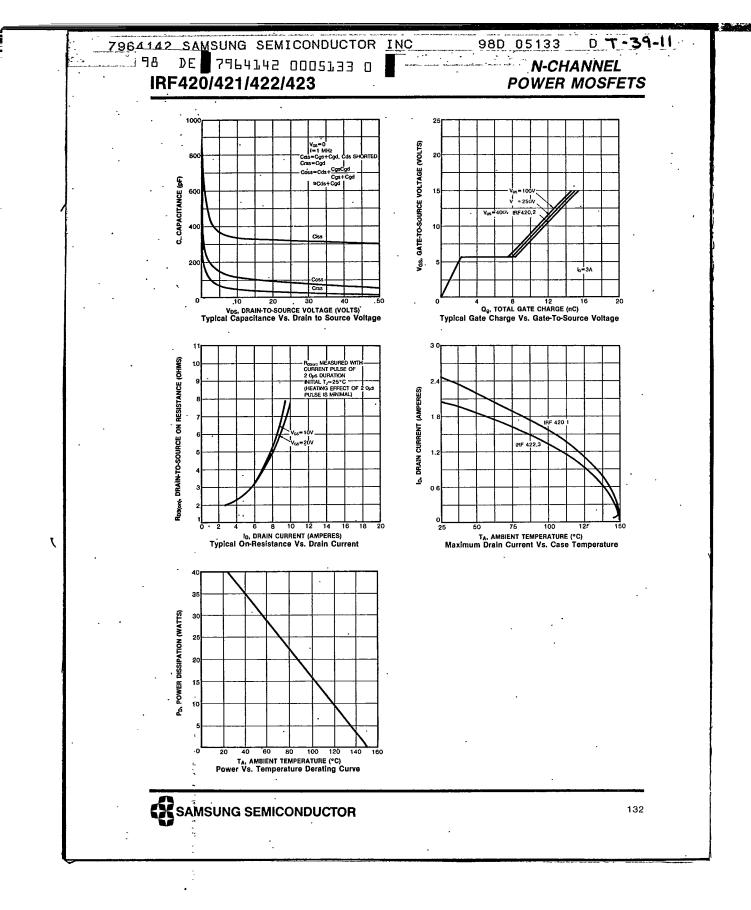
Notes: (1) TJ=25°C to 150°C (2) Pulse test: Pulse width≤300µs, Duty Cycle≤2% (3) Repetitive rating: Pulse width limited by max. junction temperature



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